

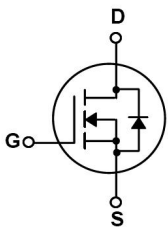
/ Descriptions

/ Features

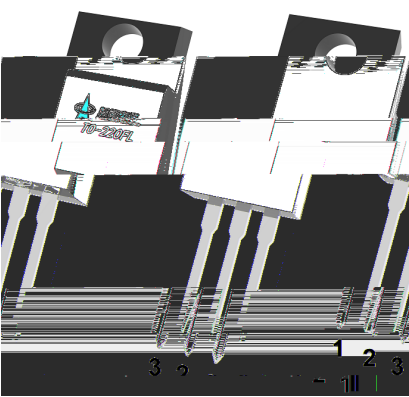
/ Applications

, UPS

/ Equivalent Circuit



/ Pinning



/ Marking

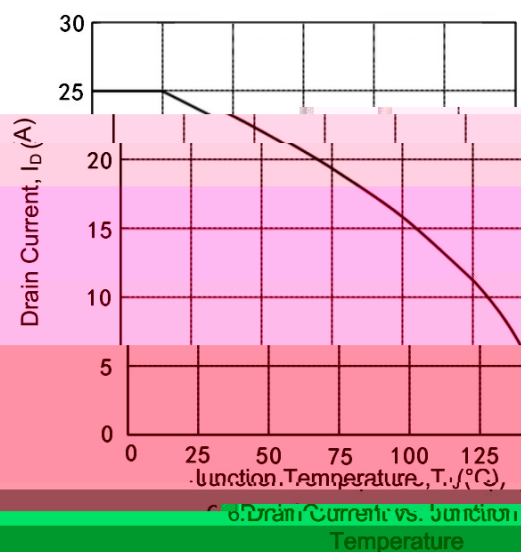
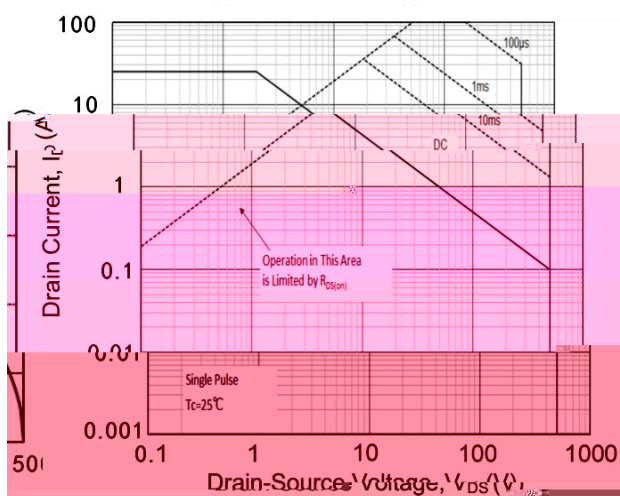
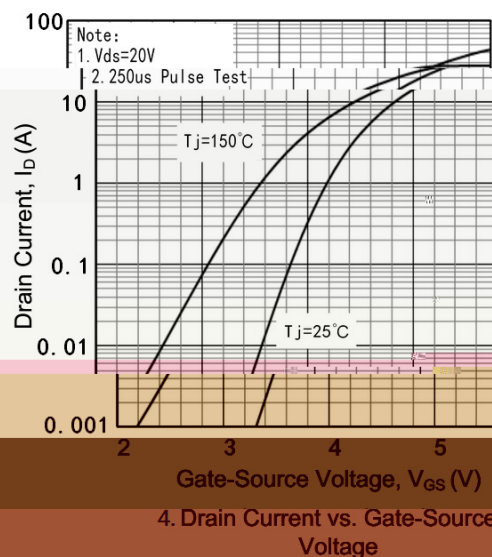
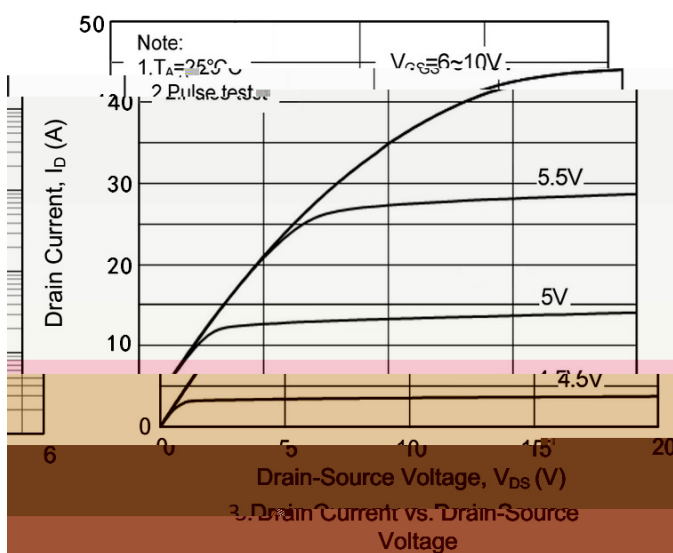
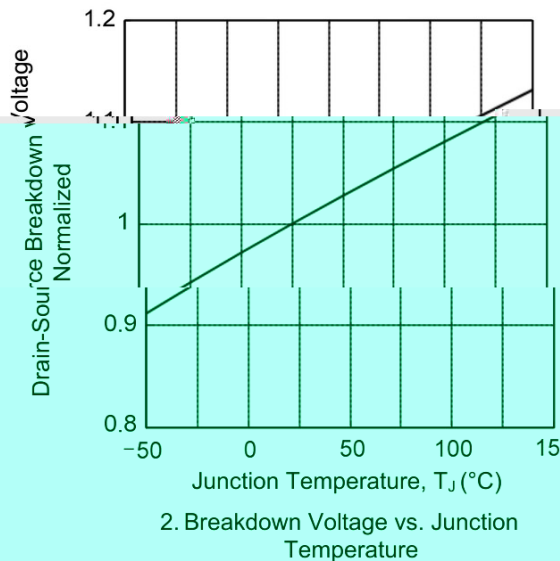
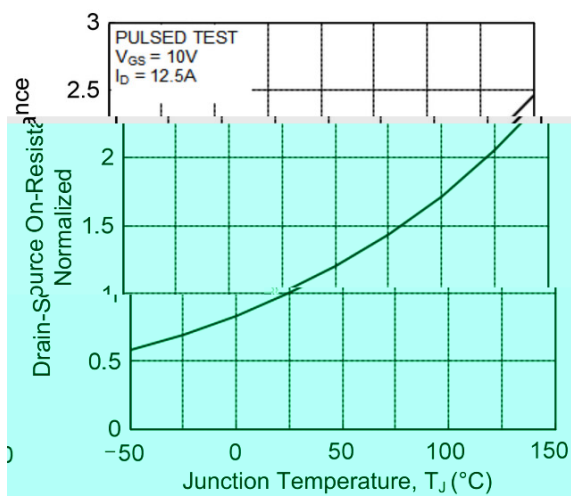
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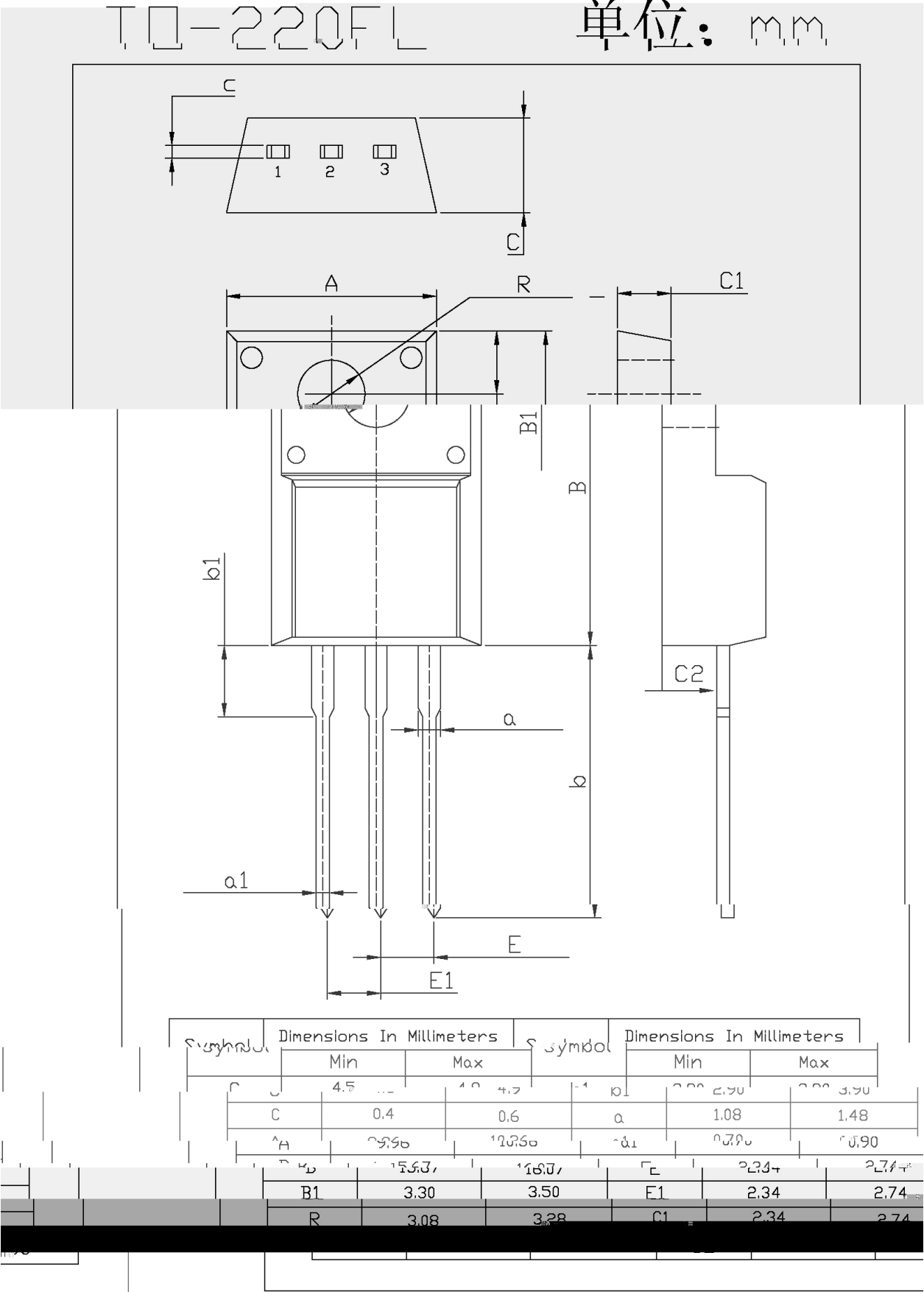
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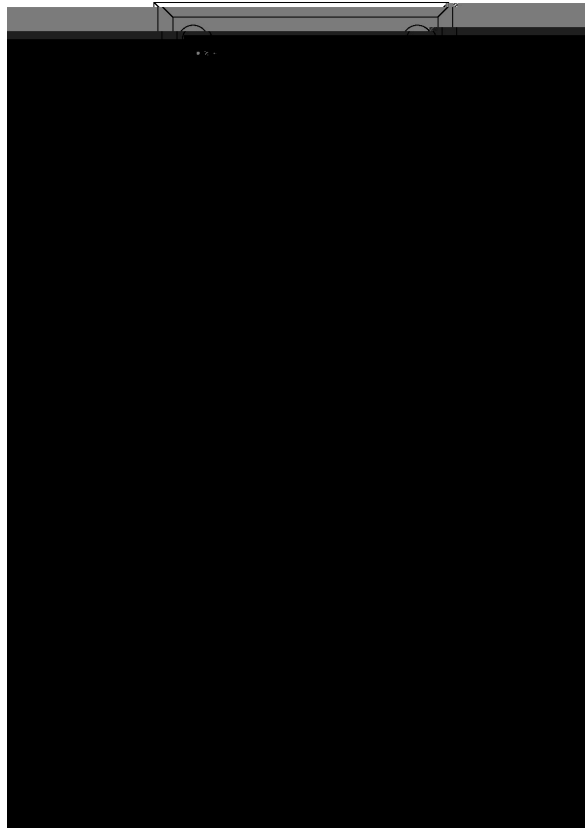
/ Electrical Characteristic Curve



/ Package Dimensions



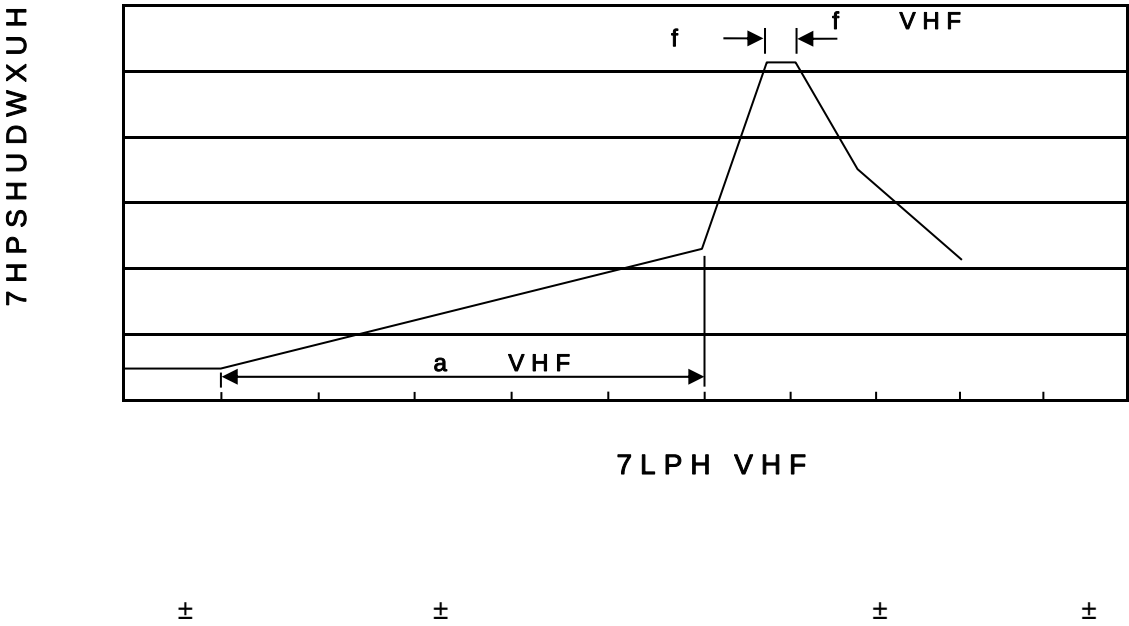
/ Marking Instructions



BR

25N50

() / Temperature Profile for Dip Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

± ± °C

/ Packaging SPEC.

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/ Notices